

***Introduction to Microsystem***

**Dr. Yi-Kuen Lee**

**Assistant Professor  
Mechanical Engineering Department  
meyklee@ust.hk**

# Outline

- **What is Microsystem technology?**
- **Why is it so popular? \$\$\$**
- **History overview**
- **Current and future applications**
- **Micro pressure sensor, accerolometer  
micro mirror arrays, inkjet printhead**
- **Microfabrication**
- **Microscience**
- **Summary and Conclusion**

## *What's in a name?*

- **MicroSystem Technology (MST)**  
popular in Europe
- **Micro-Electro-Mechanical Systems (MEMS)**  
widely used in United States
- **Microengineering**  
sometimes used in UK
- **Micromachines, マイクロマシン**  
used in Japan
- **微機電系統 in Chinese**

## ***MEMS definition***

**MEMS** is a study of making machines in micro scale with the fabrication technique in Integrated circuit (IC) industry. The size ranges from micrometer to millimeter ( $10^{-6} \sim 10^{-3}$  m)

**MEMS** are the systems that integrate

- sensing
- actuation
- computation
- control
- communication
- power

MECH106

$10^7$

$10^6$

$10^5$

$10^4$

Science

$10^3$

$10^2$

Traditional Engineering

$10^1$

$10^0$

$10^{-1}$

$10^{-2}$

$10^{-3}$

MEMS

$10^{-4}$

$10^{-5}$

$10^{-6}$

Biomedical

$10^{-7}$

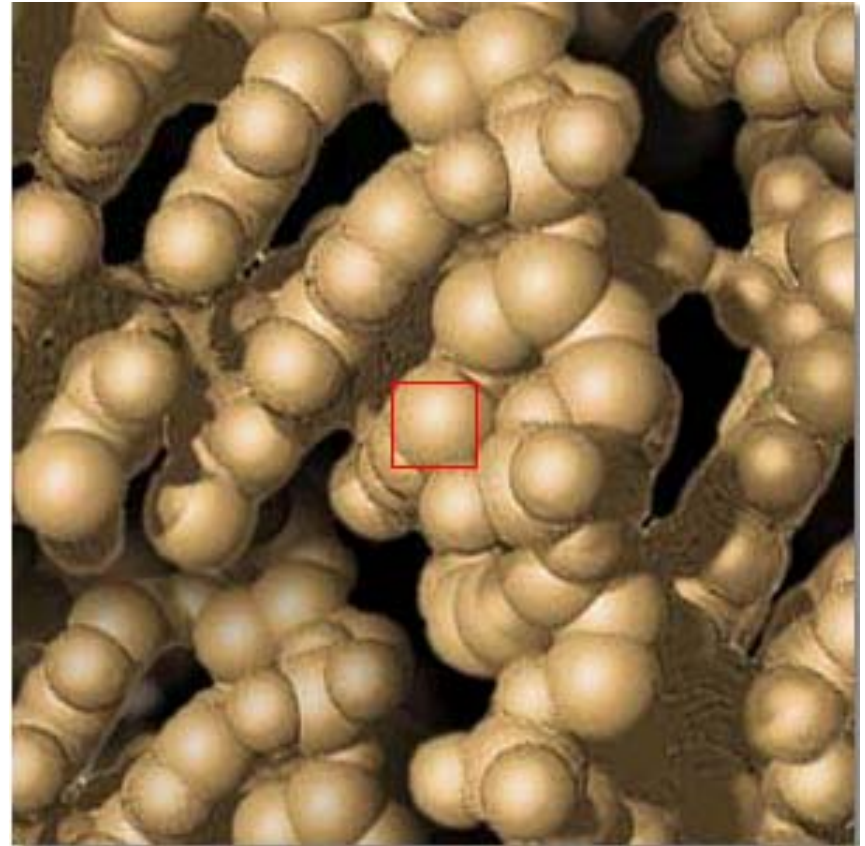
Nanotechnology

$10^{-8}$

$10^{-9}$

Unit : Meter

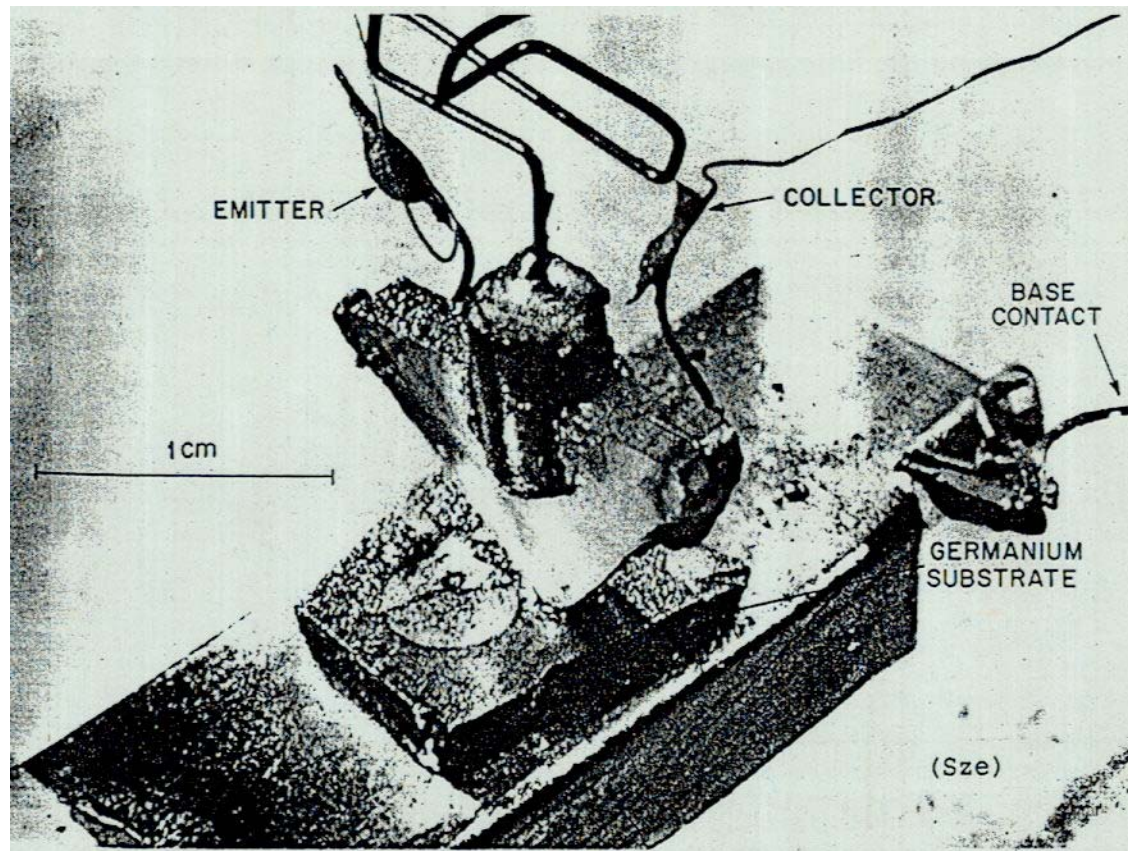
Size Does Matter



## *A brief history of MEMS*

- **1947 invention of the transistor** (made from germanium)
- **1958 silicon strain gauges commercialized; first integrated circuit (TI: Jack Kilby)**
- **1961 first silicon pressure sensor demonstrated (Kulite)**
- **1967 Invention of surface micromachining (Nathanson, Resonant Gate Transistor)**
- **1970 first silicon accelerometer demonstrated (Kulite)**
- **1977 first capacitive pressure sensor (Stanford) Prof James Angell**
- **1979 first thermal inkjet printer (HP lab)**
- **1980 Petersen, K.E., "Silicon Torsional Scanning Mirror"**
- **1982 disposable blood pressure transducer (Foxboro/ICT, Honeywell, \$40)**
- **1982 active on-chip signal conditioning**
- **1984 First polysilicon MEMS device (Howe, Muller ); HP ThinkJet**
- **1988 Rotary electrostatic side drive motors (Fan, Tai, Muller)**
- **1989 Lateral comb drive (Tang, Nguyen, Howe)**
- **1990 BIACORE microfluidic chip**
- **1991 polysilicon hinge (Pister, Judy, Burgett, Fearing)**
- **1992 Grating light modulator (Solgaard, Sandejas, Bloom), DARPA USD\$80M/yr**
- **1992 MCNC starts MUMPS**
- **1993 First surface micromachined accelerometer sold (Analog Devices, ADXL50)**
- **1996 Digital micro-mirrors array commercialized, DMD (Texas Instrument)**
- **2001 Micro optical switch for internet backbone commercialized**

## Early Semiconductor Fabrication



J. Bardeen, W.H. Brattain, "*The first transistor, a semiconductor triode*", Phys. Rev. **74**, p.230, 1948

*State-of-the-art Integrated Circuit Chip*

Intel®  
Pentium 4  
Processor

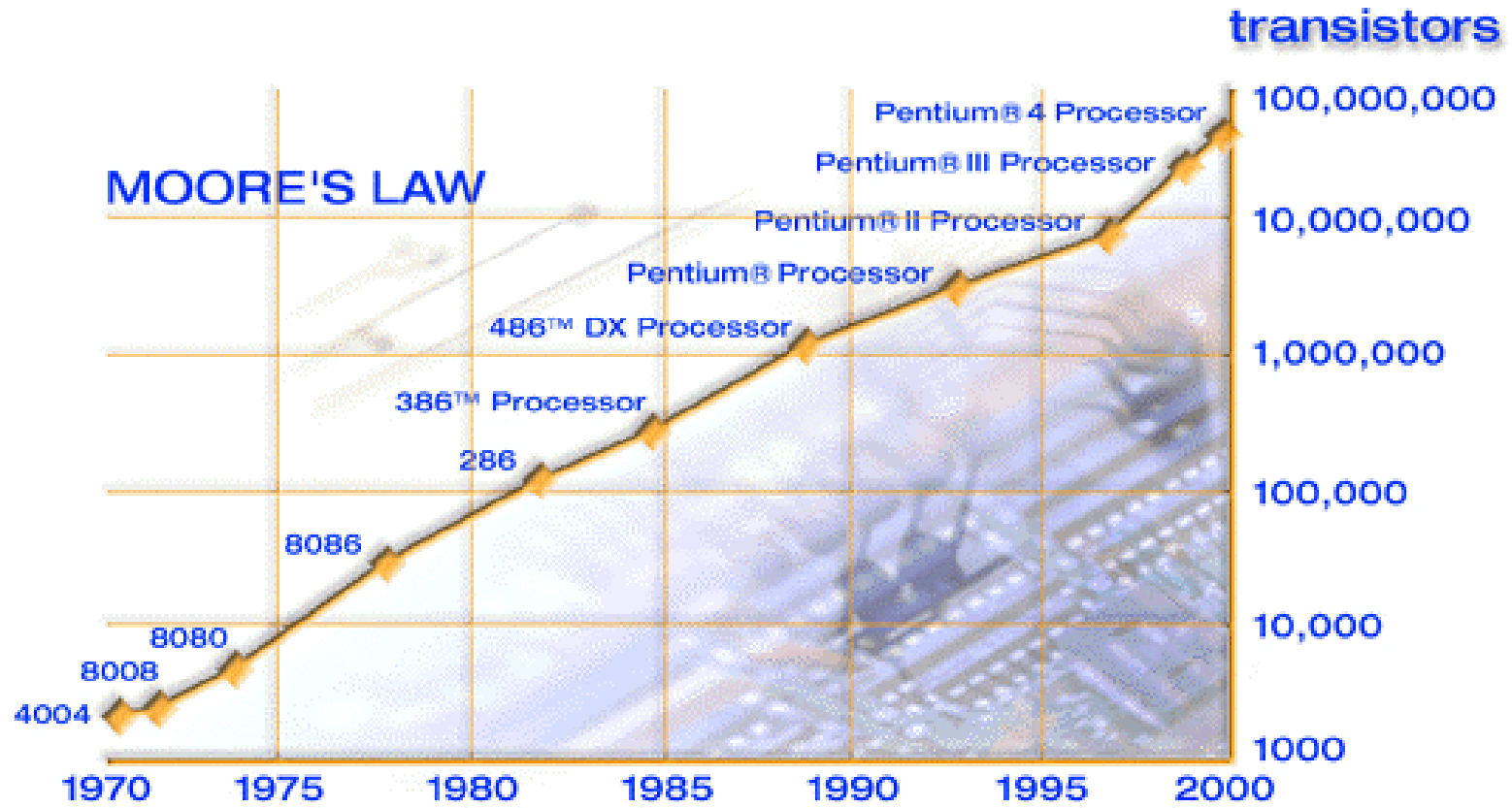
42 million transistors  
0.18 micron  
lithography  
2001



<http://www.tomshardware.com/cpu/01q2/010423/p4-01.html>

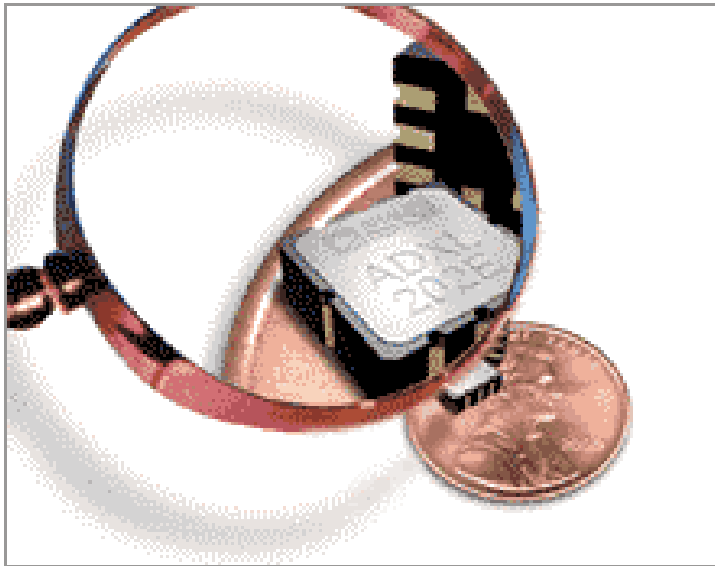


# Moore's Law for IC Chip



**CPU power doubles every 18 months**  
**How about MEMS?**

## State-of-the-art MEMS Chips

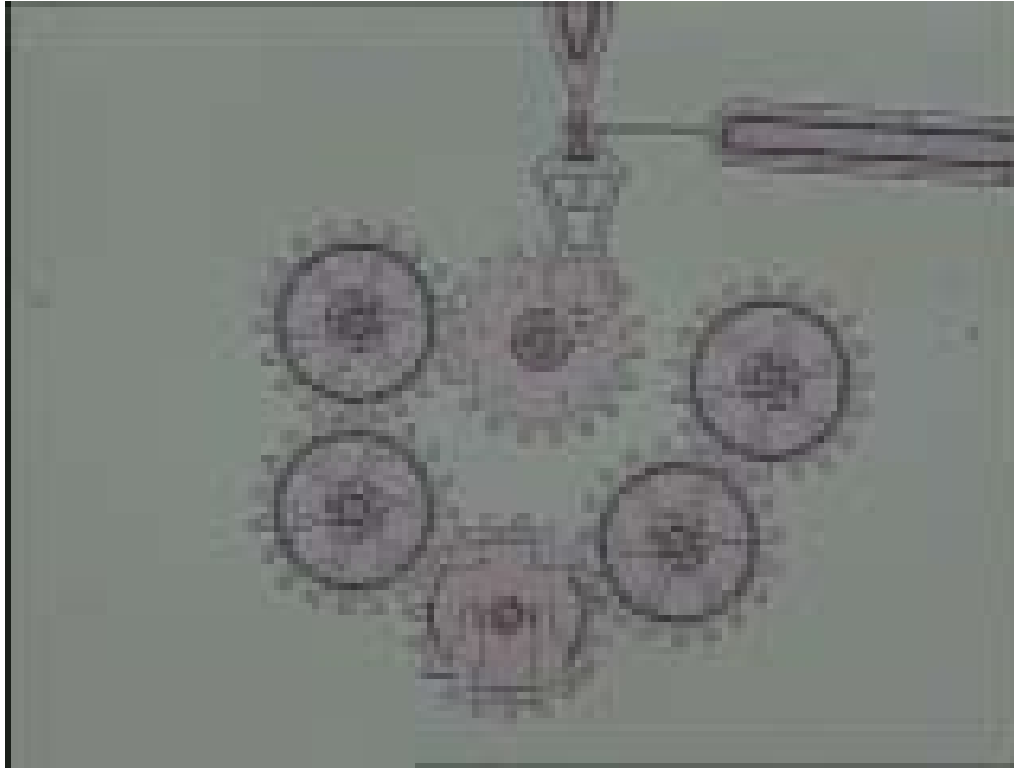


Analog Devices  
ADXL202  
micro-accelerometer



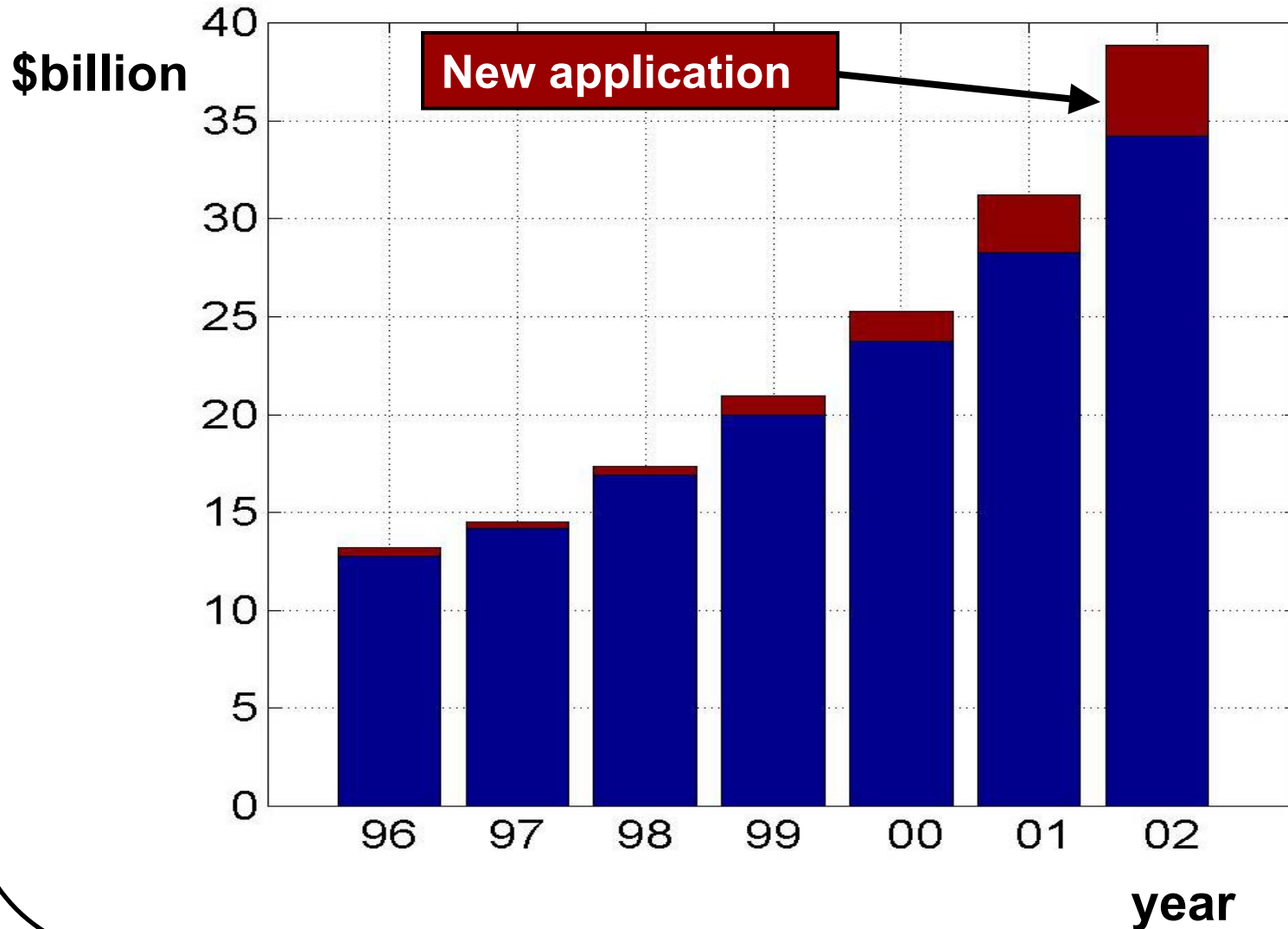
Texas Instrument  
Digital light processing  
~ 1 million mirrors

*Microgears driven by a microengine*

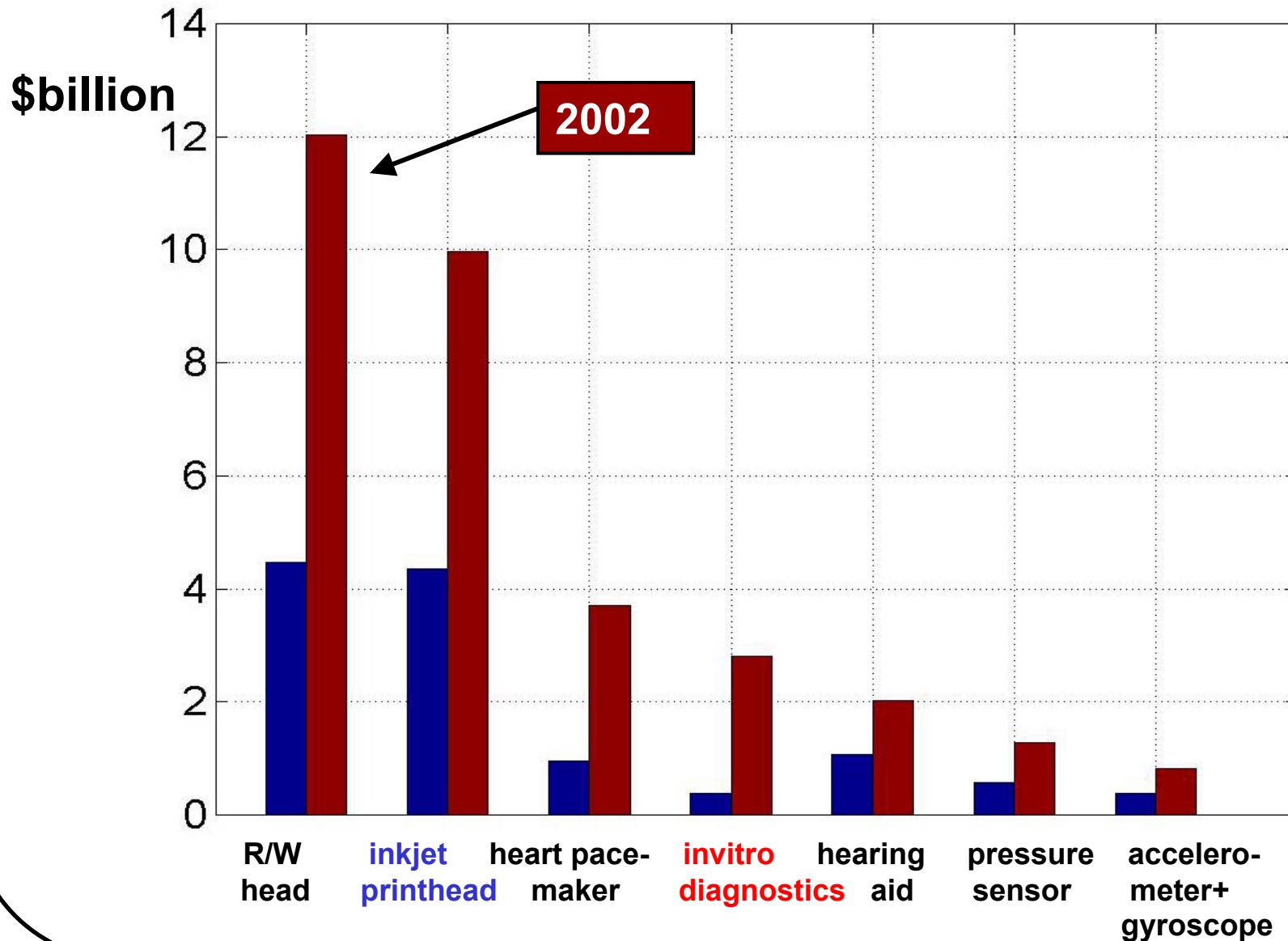


**US Sandia National Lab MEMS project for nuclear weapon security**

# MEMS market analysis by NEXUS



# MEMS market volumes in 1996 & 2002



## ***Current MEMS applications***

- **Pressure sensors, disposable blood pressure**
- **Accelerometers, air-bag deployment**
- **Ink-jet printer heads**
- **Digital micromirrors for computer projectors**
- **Portable clinical analyzers**
- **DNA microarray**

## ***More applications***

- **Inertial guidance microdevices: microgyroscope**
- **Active magnetic head for ultra high density hard-drive**
- **Optical switches for internet backbone system**
- **Flow control, drag reduction**
- **Bio-chemical lab-on-a-chip**
- **Communication components:**  
micromechanical filters, RF-switches & relays
- **Power MEMS:**  
microfuel cells, micro generators
- **Military MEMS:**  
micro NBC (nuclear, bacterial and chemical) detectors

# Traditional Uses of MEMS

Airbag deployment  
MEMS accelerometer

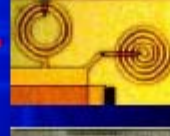


Stability Control System  
MEMS micro-gyro

MEMS Pressure Sensor



# *Future Potential Uses of MEMS*



**Antennas**

**Color bi-stable display**

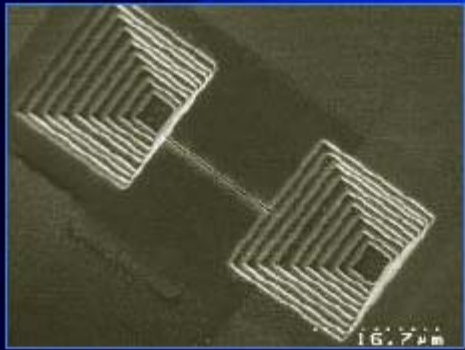
**Micro-switches**

**Tunable capacitors  
and inductors**

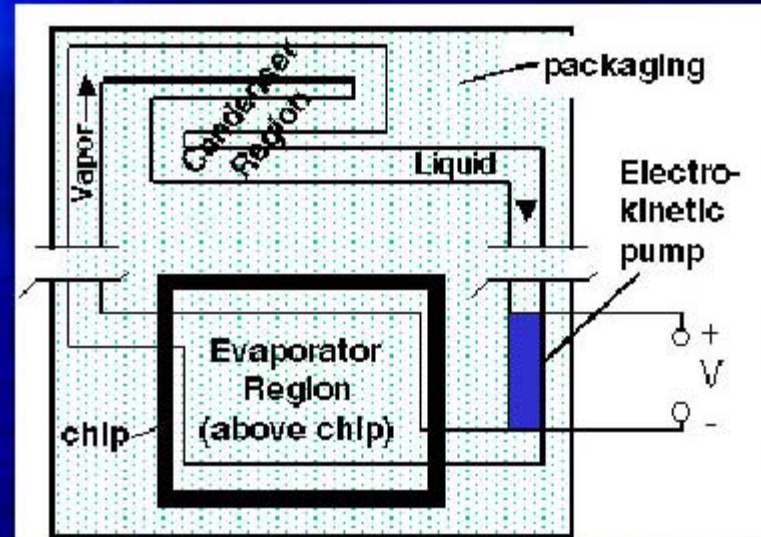
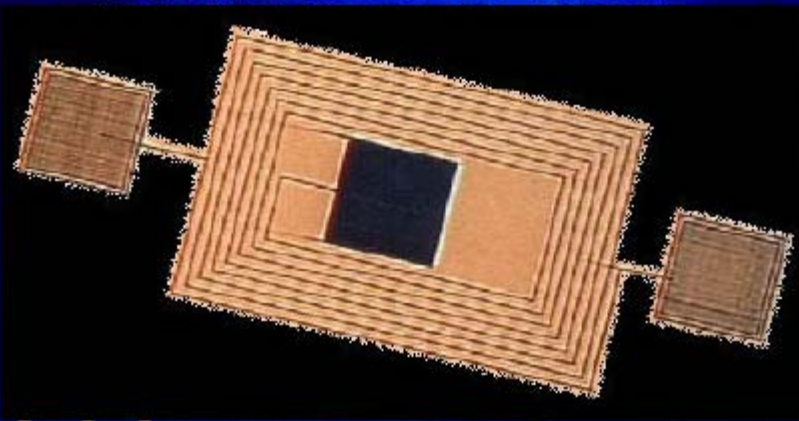
**Tunable filters**

**Directional microphone**

# Potential for Chip Cooling, BioMEMS

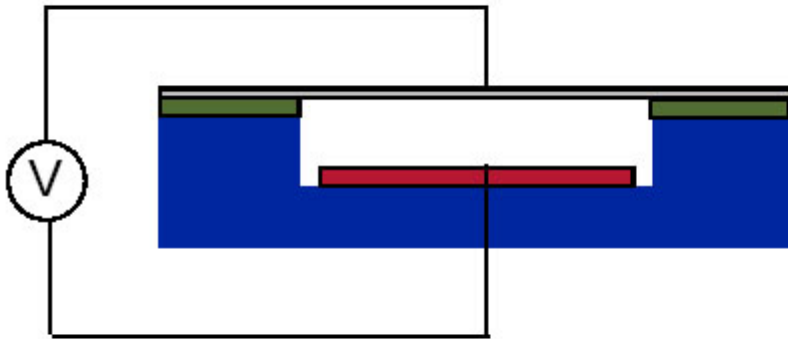


Micro-fluidics devices fabricated at Intel



Micro-refrigerator (Research at Stanford University)

# *Micro pressure sensors*



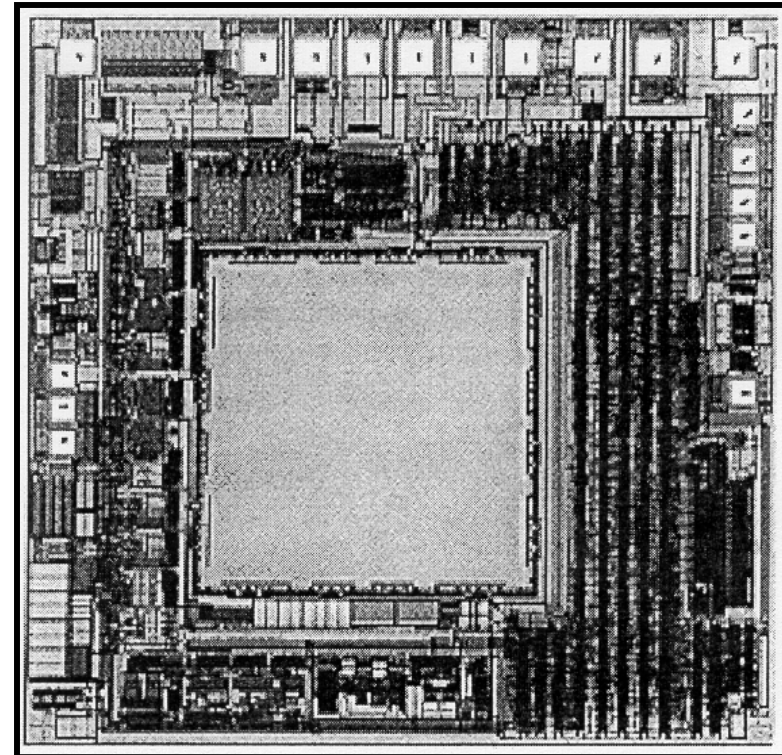
Capacitive sensing



Piezoresistive sensing

# Integrated Pressure Sensors

- Silicon pressure sensors have been on the market for over 30 years
- First integration attempt
  - late 1970's
- Over 100 million units are now produced every year
- A significant portion of which has on-chip integration ranging from
  - Passive trim elements only
  - Analog signal conditioning
  - Digital signal conditioning



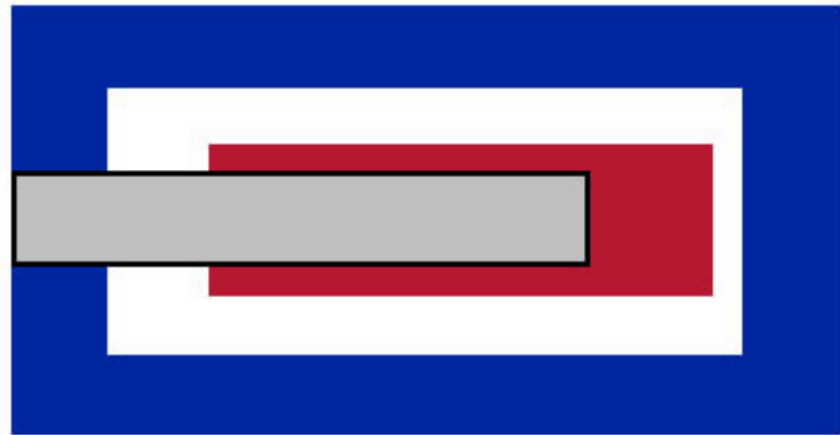
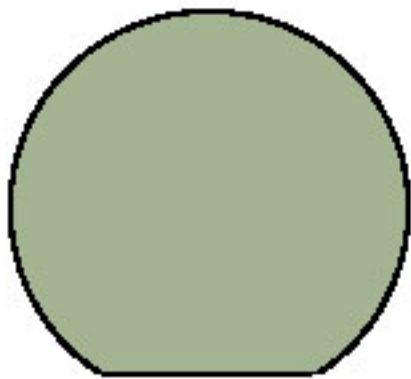
**Motorola's latest  
Automotive Pressure Sensor  
with DSP**

# Micro accelerometer

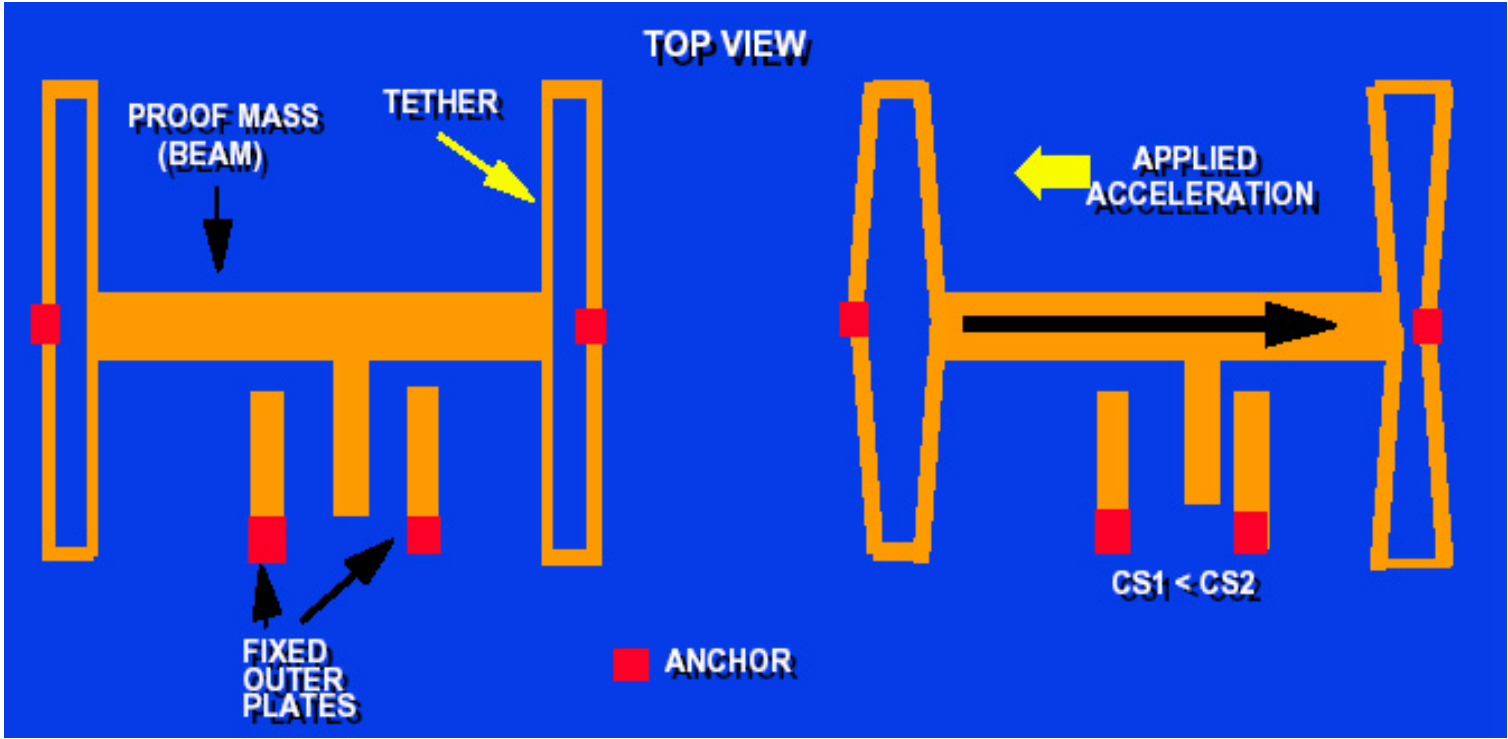
Side view



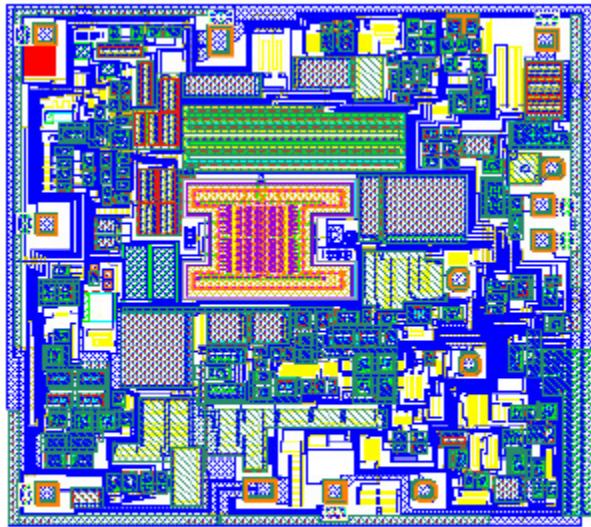
Top view



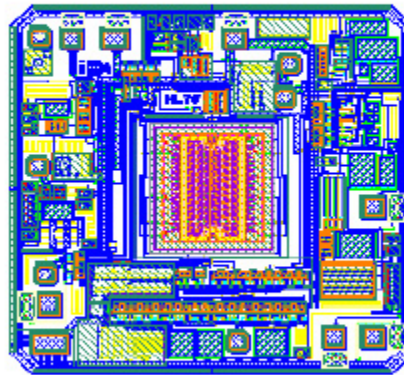
# Micro accelerometer practical design



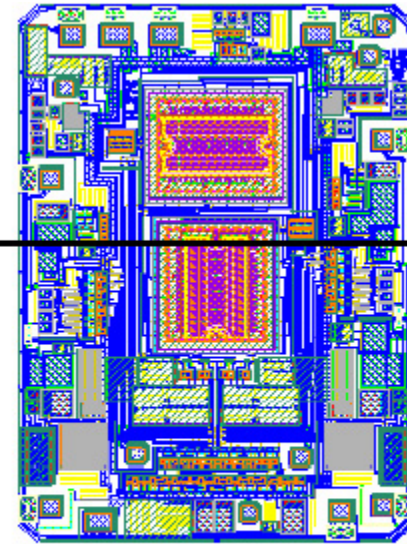
# ADI Automotive Accelerometers



**XL50**  
Original  
**1993**

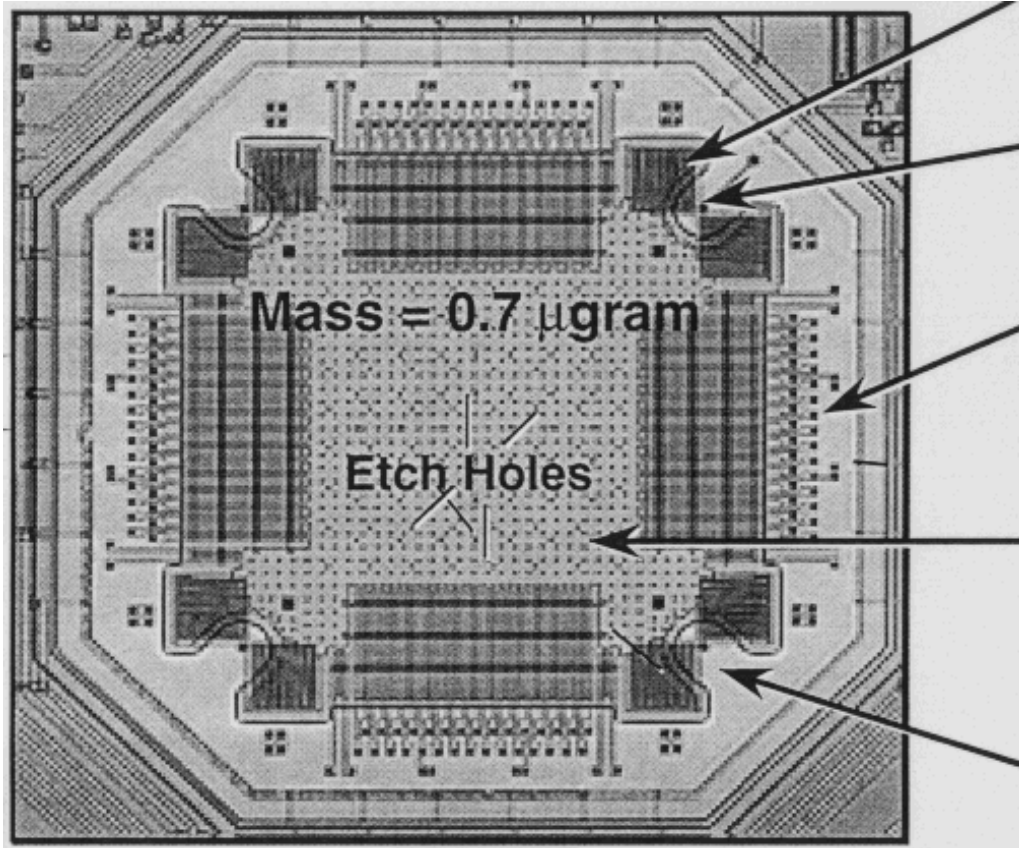


**XL150**  
New  
**~1996**



**XL250**  
2 Channel New  
**~1997**

# ADXL202 Beam structure



Tether (Spring)

Anchor point

30 sensing cells per axis  
1.2μm gaps,  
1μm feature size

2μm thick polysilicon  
structure suspended  
1.6μm above substrate

10kHz resonant  
frequency

**Deflection due to 2g acceleration = 5nm = 250·10<sup>-18</sup>F**

**Minimum resolvable deflection = 0.04A = 90·10<sup>-21</sup>F**